



## Remote 8-bit I/O expander for I<sup>2</sup>C-bus

#### FEATURES

- Operating supply voltage 2.5 to 6 V
- Low standby current consumption of 10  $\mu$ A maximum
- I<sup>2</sup>C to parallel port expander
- Open-drain interrupt output
- 8-bit remote I/O port for the I<sup>2</sup>C-bus
- · Compatible with most microcontrollers
- Latched outputs with high current drive capability for directly driving LEDs
- Address by 3 hardware address pins for use of up to 8 devices (up to 16 with PCF8574A)
- DIP16, or space-saving SOP16 or SSOP20 packages.

## **GENERAL DESCRIPTION**

The PCF8574 is a silicon CMOS circuit. It provides general purpose remote I/O expansion for most microcontroller families via the two-line bidirectional bus (I<sup>2</sup>C).

The device consists of an 8-bit quasi-bidirectional port and an l<sup>2</sup>C-bus interface. The PCF8574 has a low current consumption and includes latched outputs with high current drive capability for directly driving LEDs. It also possesses an interrupt line ( $\overline{INT}$ ) which can be connected to the interrupt logic of the microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the l<sup>2</sup>C-bus. This means that the PCF8574 can remain a simple slave device.

The PCF8574 and PCF8574A versions differ only in their slave address as shown in Fig.9.

#### **ORDERING INFORMATION**

DEVICE	Package Type	MARKING	Packing	Packing Qty
PCF8574AN	DIP16L	PCF8574A	TUBE	1000pcs/box
PCF8574AT/TR	SOP16W	PCF8574A	REEL	2000pcs/reel
PCF8574AM/TR	SOP16L	PCF8574A	REEL	2500pcs/reel
PCF8574AMS/TR	SSOP20L	PCF8574A	REEL	2000pcs/reel
PCF8574N	DIP16L	PCF8574	TUBE	1000pcs/box
PCF8574T/TR	SOP16W	PCF8574	REEL	2000pcs/reel
PCF8574M/TR	SOP16L	PCF8574	REEL	2500pcs/reel
PCF8574MS/TR	SSOP20L	PCF8574	REEL	2000pcs/reel

## **BLOCK DIAGRAM**

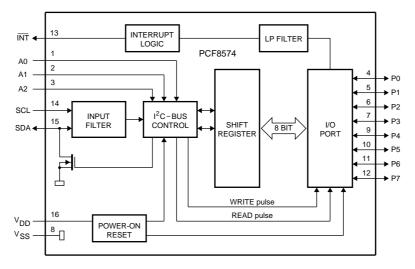


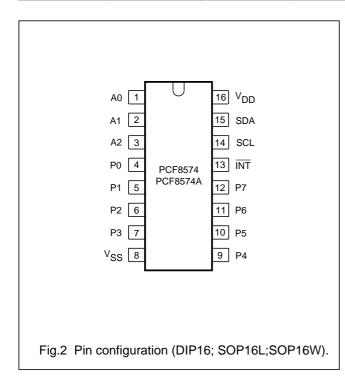
Fig.1 Block diagram (SOT38-1 and SOT162-1).

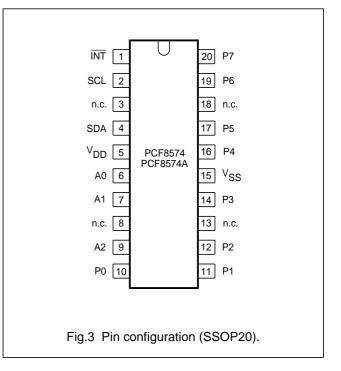


# PCF8574

#### PINNING

SYMBOL	PIN		DESCRIPTION		
STNIDOL	DIP16; SOP16	SSOP20	DESCRIPTION		
A0	1	6	address input 0		
A1	2	7	address input 1		
A2	3	9	address input 2		
P0	4	10	quasi-bidirectional I/O 0		
P1	5	11	quasi-bidirectional I/O 1		
P2	6	12	quasi-bidirectional I/O 2		
P3	7	14	quasi-bidirectional I/O 3		
V <sub>SS</sub>	8	15	supply ground		
P4	9	16	quasi-bidirectional I/O 4		
P5	10	17	quasi-bidirectional I/O 5		
P6	11	19	quasi-bidirectional I/O 6		
P7	12	20	quasi-bidirectional I/O 7		
ĪNT	13	1	interrupt output (active LOW)		
SCL	14	2	serial clock line		
SDA	15	4	serial data line		
V <sub>DD</sub>	16	5	supply voltage		
n.c.	-	3	not connected		
n.c.	-	8	not connected		
n.c.	-	13	not connected		
n.c.	-	18	not connected		







#### CHARACTERISTICS OF THE I <sup>2</sup>C-BUS

The I<sup>2</sup>C-bus is for 2-way, 2-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

#### Bit transfer

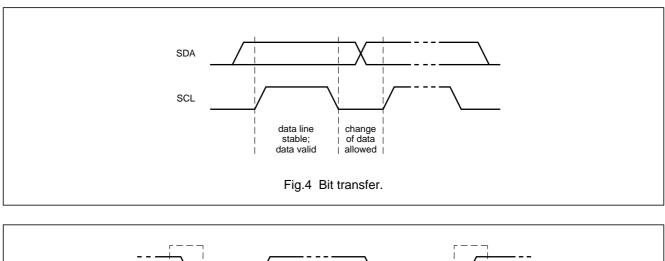
One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals (see Fig.4).

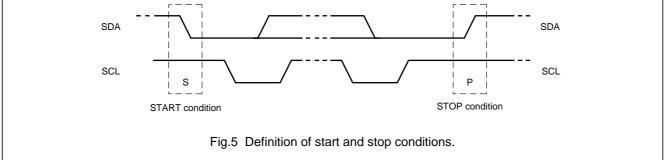
#### Start and stop conditions

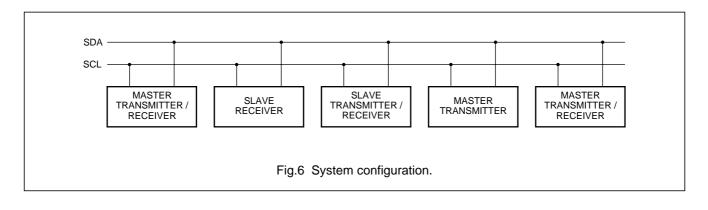
Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line, while the clock is HIGH is defined as the start condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the stop condition (P) (see Fig.5).

### System configuration

A device generating a message is a 'transmitter', a device receiving is the 'receiver'. The device that controls the message is the 'master' and the devices which are controlled by the master are the 'slaves' (see Fig.6).







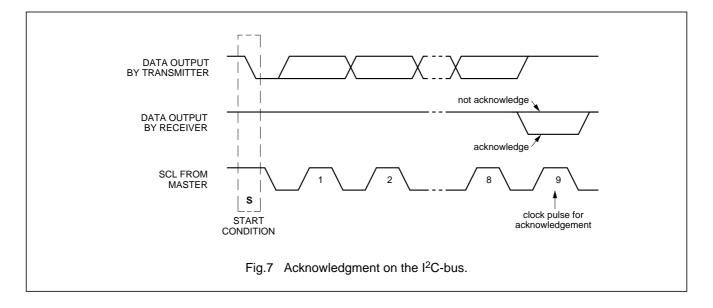


#### Acknowledge

The number of data bytes transferred between the start and the stop conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level put on the bus by the transmitter whereas the master generates an extra acknowledge related clock pulse.

A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse, set-up and hold times must be taken into account.

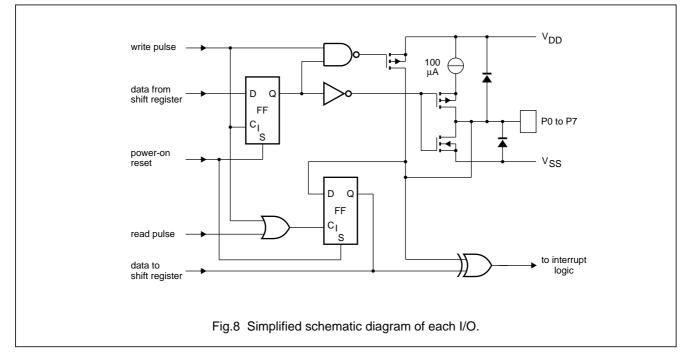
A master receiver must signal an end of data to the transmitter by **not** generating an acknowledge on the last byte that has been clocked out of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a stop condition.





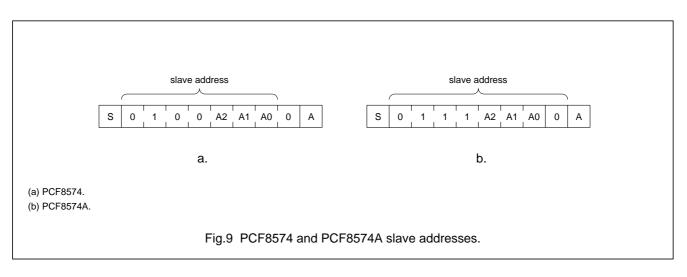
PCF8574

## FUNCTIONAL DESCRIPTION



## Addressing

For addressing see Figs 9, 10 and 11.



Each of the PCF8574's eight I/Os can be independently used as an input or output. Input data is transferred from the port to the microcontroller by the READ mode (see Fig.11). Output data is transmitted to the port by the WRITE mode (see Fig.10).



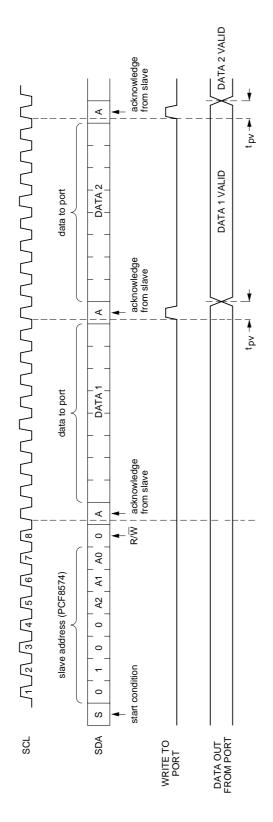


Fig.10 WRITE mode (output).

PCF8574



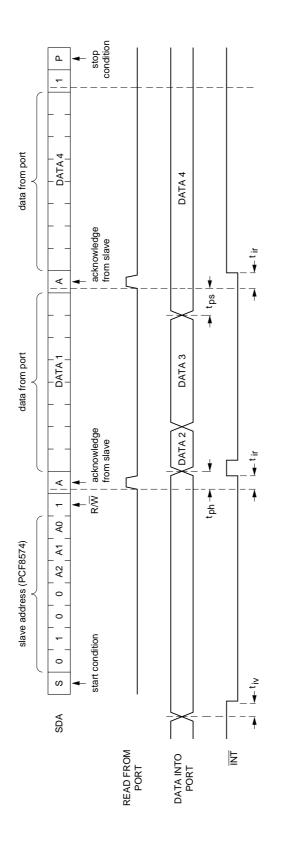


Fig.11 READ mode (input).

A LOW-to-HIGH transition of SDA, while SCL is HIGH is defined as the stop condition (P). Transfer of data can be stopped at any moment by a stop condition. When this occurs, data present at the last acknowledge phase is valid (output mode). Input data is lost.

### **Interrupt** (see Figs 12 and 13)

The PCF8574 provides an open drain output (INT) which can be fed to a corresponding input of the microcontroller. This gives these chips a type of master function which can initiate an action elsewhere in the system.

An interrupt is generated by any rising or falling edge of the port inputs in the input mode. After time  $t_{iv}$  the signal  $\overline{INT}$  is valid.

Resetting and reactivating the interrupt circuit is achieved when data on the port is changed to the original setting or data is read from or written to the port which has generated the interrupt.

Resetting occurs as follows:

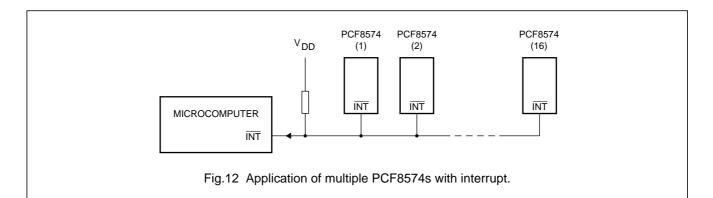
- In the READ mode at the acknowledge bit after the rising edge of the SCL signal
- In the WRITE mode at the acknowledge bit after the HIGH-to-LOW transition of the SCL signal

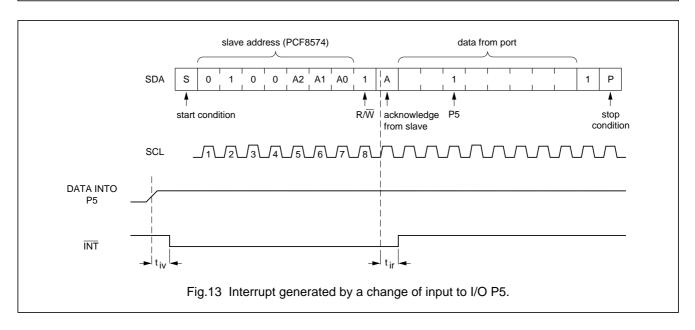
• Interrupts which occur during the acknowledge clock pulse may be lost (or very short) due to the resetting of the interrupt during this pulse.

Each change of the I/Os after resetting will be detected and, after the next rising clock edge, will be transmitted as INT. Reading from or writing to another device does not affect the interrupt circuit.

## Quasi-bidirectional I/Os (see Fig.14)

A quasi-bidirectional I/O can be used as an input or output without the use of a control signal for data direction. At power-on the I/Os are HIGH. In this mode only a current source to  $V_{DD}$  is active. An additional strong pull-up to  $V_{DD}$  allows fast rising edges into heavily loaded outputs. These devices turn on when an output is written HIGH, and are switched off by the negative edge of SCL. The I/Os should be HIGH before being used as inputs.







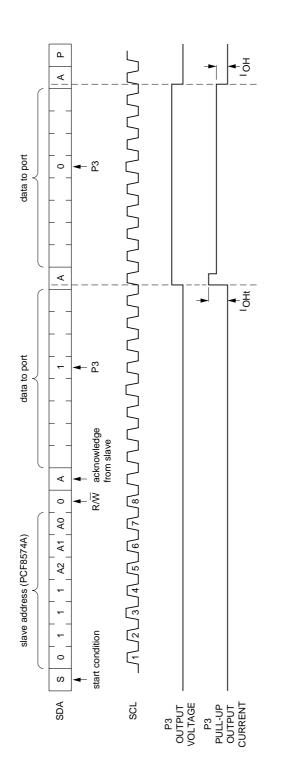


Fig.14 Transient pull-up current I<sub>OHt</sub> while P3 changes from LOW-to-HIGH and back to LOW.



## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>DD</sub>	supply voltage	-0.5	+7.0	V
VI	input voltage	V <sub>SS</sub> – 0.5	V <sub>DD</sub> + 0.5	V
l <sub>l</sub>	DC input current	_	±20	mA
I <sub>O</sub>	DC output current	_	±25	mA
I <sub>DD</sub>	supply current	_	±100	mA
I <sub>SS</sub>	supply current	_	±100	mA
P <sub>tot</sub>	total power dissipation	-	400	mW
Po	power dissipation per output	-	100	mW
T <sub>stg</sub>	storage temperature	-65	+150	°C
T <sub>amb</sub>	operating ambient temperature	-40	+85	°C

#### HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take precautions appropriate to handling MOS devices. Advice can be found in Data Handbook IC12 under *"Handling MOS Devices"*.

## DC CHARACTERISTICS

 $V_{DD}$  = 2.5 to 6 V;  $V_{SS}$  = 0 V;  $T_{amb}$  = –40 to +85 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						•
V <sub>DD</sub>	supply voltage		2.5	-	6.0	V
I <sub>DD</sub>	supply current	operating mode; $V_{DD} = 6 V$ ; no load; $V_I = V_{DD}$ or $V_{SS}$ ; $f_{SCL} = 100 \text{ kHz}$	_	40	100	μA
l <sub>stb</sub>	standby current	standby mode; $V_{DD} = 6 V$ ; no load; $V_I = V_{DD}$ or $V_{SS}$	-	2.5	10	μA
V <sub>POR</sub>	Power-on reset voltage	$V_{DD} = 6 V$ ; no load; $V_{I} = V_{DD}$ or $V_{SS}$ ; note 1	-	1.3	2.4	V
Input SCL;	input/output SDA	•	•	•	•	
V <sub>IL</sub>	LOW level input voltage		-0.5	_	+0.3V <sub>DD</sub>	V
V <sub>IH</sub>	HIGH level input voltage		0.7V <sub>DD</sub>	-	V <sub>DD</sub> + 0.5	V
I <sub>OL</sub>	LOW level output current	V <sub>OL</sub> = 0.4 V	3	-	-	mA
IL	leakage current	$V_{I} = V_{DD} \text{ or } V_{SS}$	-1	-	+1	μA
C <sub>i</sub>	input capacitance	$V_{I} = V_{SS}$	-	-	7	pF



SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I/Os			•	•		-1
V <sub>IL</sub>	LOW level input voltage		-0.5	_	+0.3V <sub>DD</sub>	V
V <sub>IH</sub>	HIGH level input voltage		0.7V <sub>DD</sub>	-	V <sub>DD</sub> + 0.5	V
I <sub>IHL(max)</sub>	maximum allowed input current through protection diode	$V_{I} \ge V_{DD}$ or $V_{I} \le V_{SS}$	-	-	±400	μΑ
I <sub>OL</sub>	LOW level output current	V <sub>OL</sub> = 1 V; V <sub>DD</sub> = 5 V	10	25	-	mA
I <sub>OH</sub>	HIGH level output current	$V_{OH} = V_{SS}$	30	-	300	μA
I <sub>OHt</sub>	transient pull-up current	HIGH during acknowledge (see Fig.14); $V_{OH} = V_{SS}$ ; $V_{DD} = 2.5 V$	-	-1	-	mA
Ci	input capacitance		_	_	10	pF
Co	output capacitance		-	_	10	pF
Port timing	; $C_L \le 100 \text{ pF}$ (see Figs 10 an	d 11)				
t <sub>pv</sub>	output data valid		_	-	4	μs
t <sub>su</sub>	input data set-up time		0	-	-	μs
t <sub>h</sub>	input data hold time		4	_	-	μs
Interrupt IN	T (see Fig.13)					
I <sub>OL</sub>	LOW level output current	V <sub>OL</sub> = 0.4 V	1.6	-	-	mA
IL	leakage current	$V_{I} = V_{DD} \text{ or } V_{SS}$	-1	_	+1	μA
TIMING; C <sub>L</sub> ≤	100 PF					
t <sub>iv</sub>	input data valid time		-	_	4	μs
t <sub>ir</sub>	reset delay time		-	-	4	μs
Select inpu	ts A0 to A2					
V <sub>IL</sub>	LOW level input voltage		-0.5	-	+0.3V <sub>DD</sub>	V
V <sub>IH</sub>	HIGH level input voltage		0.7V <sub>DD</sub>	-	V <sub>DD</sub> + 0.5	V
ILI	input leakage current	pin at V <sub>DD</sub> or V <sub>SS</sub>	-250	-	+250	nA

Note

1. The Power-on reset circuit resets the l<sup>2</sup>C-bus logic with  $V_{DD} < V_{POR}$  and sets all I/Os to logic 1 (with current source to  $V_{DD}$ ).

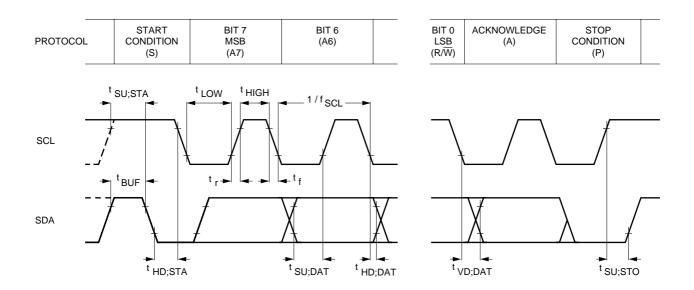


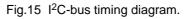
## I<sup>2</sup>C-BUS TIMING CHARACTERISTICS

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
I <sup>2</sup> C-BUS TIM	IING (see Fig.15; note 1)			- 4	-
f <sub>SCL</sub>	SCL clock frequency	-	-	100	kHz
t <sub>SW</sub>	tolerable spike width on bus	-	-	100	ns
t <sub>BUF</sub>	bus free time	4.7	-	-	μs
t <sub>SU;STA</sub>	START condition set-up time	4.7	-	-	μs
t <sub>HD;STA</sub>	START condition hold time	4.0	-	-	μs
t <sub>LOW</sub>	SCL LOW time	4.7	-	-	μs
t <sub>HIGH</sub>	SCL HIGH time	4.0	-	-	μs
t <sub>r</sub>	SCL and SDA rise time	_	-	1.0	μs
t <sub>f</sub>	SCL and SDA fall time	-	-	0.3	μs
t <sub>SU;DAT</sub>	data set-up time	250	-	-	ns
t <sub>HD;DAT</sub>	data hold time	0	-	-	ns
t <sub>VD;DAT</sub>	SCL LOW to data out valid	-	-	3.4	μs
t <sub>SU;STO</sub>	STOP condition set-up time	4.0	-	-	μs

#### Note

1. All the timing values are valid within the operating supply voltage and ambient temperature range and refer to  $V_{IL}$  and  $V_{IH}$  with an input voltage swing of  $V_{SS}$  to  $V_{DD}$ .

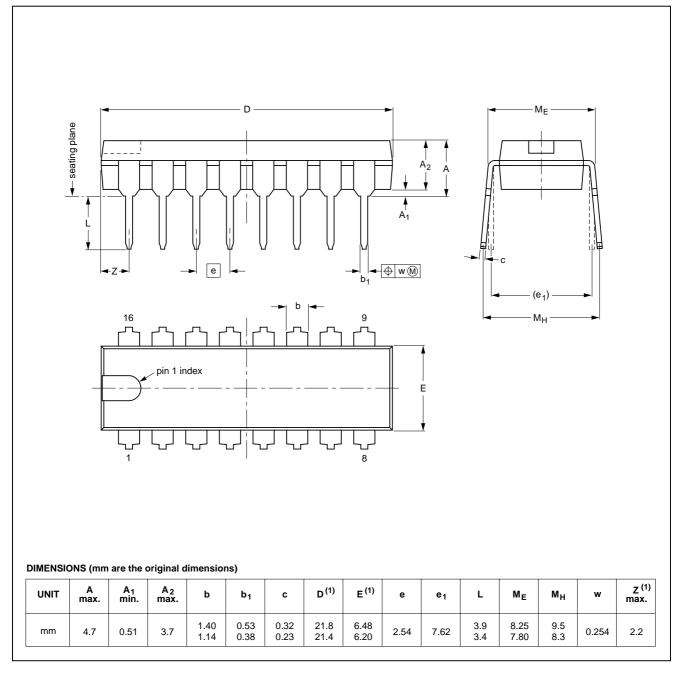






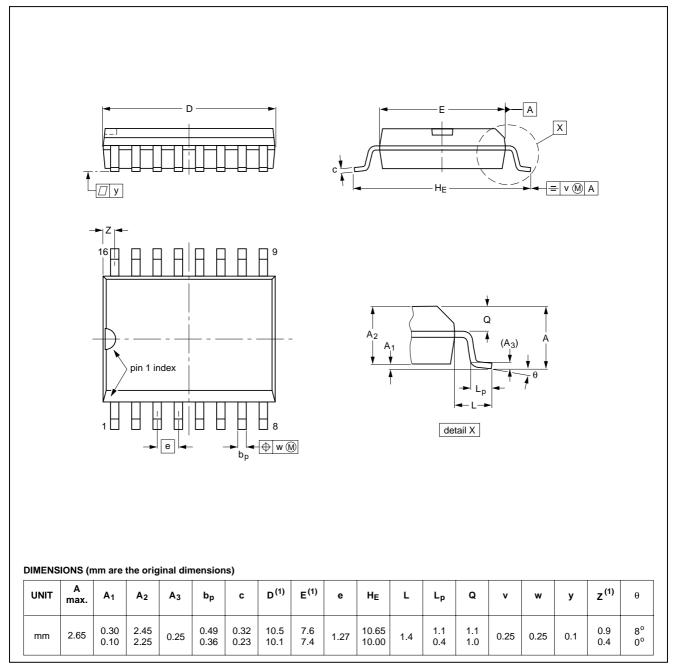
## PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil); long body



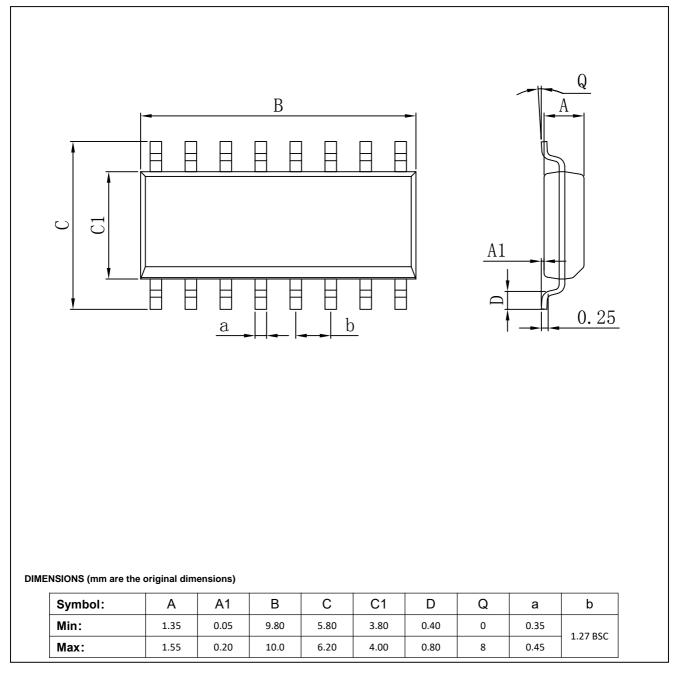


## SOP16W: plastic small outline package; 16 leads; body width 7.5 mm



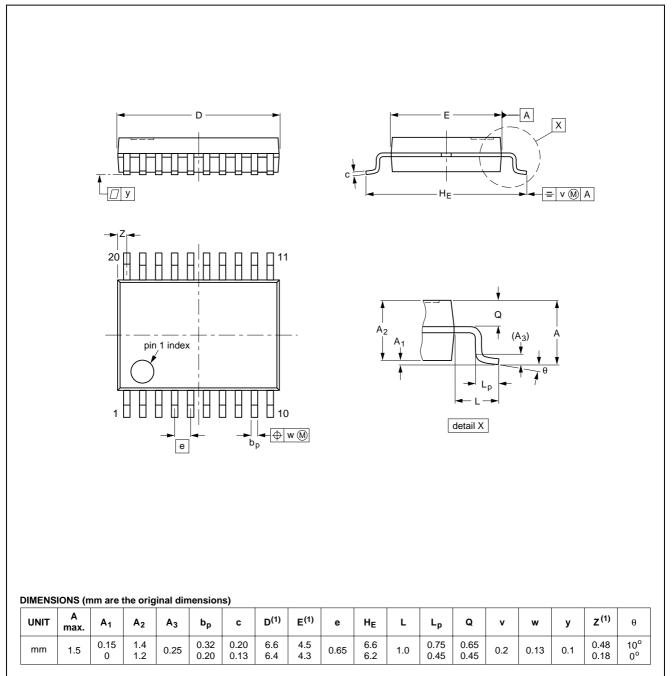


## SOP16L: plastic small outline package; 16 leads; body width 3.9 mm





## SSOP20: plastic shrink small outline package; 20 leads; body width 4.4 mm





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